

1-5645953-2 ✓ ACTIVE

TE Internal #: 1-5645953-2

4.01 mm [.158 in] Socket Length, 1.32 mm [.052 in] PCB Hole, Bullet

Nose, .162 – .326 mm<sup>2</sup> Wire, 25 – 22 AWG, Cable-to-Board, Pin

Sockets

[View on TE.com >](#)



Connectors > Socket Connectors > Pin Sockets > Miniature Spring Sockets: Bullet Nose, Beryllium Copper, 4A



Socket Length: 4.01 mm [.158 in]

PCB Hole Diameter: 1.32 mm [.052 in]

Socket Sleeve Style: **Bullet Nose**

Wire Size: 25 – 22 AWG

[All Miniature Spring Sockets: Bullet Nose, Beryllium Copper, 4A \(14\)](#)

## Features

### Product Type Features

|                                   |                       |
|-----------------------------------|-----------------------|
| Connector & Contact Terminates To | Printed Circuit Board |
| Socket Sleeve Style               | Bullet Nose           |
| Connector System                  | Cable-to-Board        |
| Sealable                          | No                    |

### Configuration Features

|                                   |               |
|-----------------------------------|---------------|
| Compatible With Wire & Cable Type | Discrete Wire |
|-----------------------------------|---------------|

### Body Features

|                         |        |
|-------------------------|--------|
| Sleeve Plating Material | Tin    |
| Sleeve Material         | Copper |

### Contact Features

|  |                  |
|--|------------------|
| Contact Spring Plating Material                | Gold             |
| Contact Base Material                          | Beryllium Copper |
| Contact Mating Area Plating Material Thickness | 30 μm[30 μin]    |
| Contact Spring Plating Thickness               | .762 μm[30 μin]  |



|                              |     |
|------------------------------|-----|
| Contact Current Rating (Max) | 4 A |
|------------------------------|-----|

### Termination Features

|                           |                          |
|---------------------------|--------------------------|
| Termination Method to PCB | Through Hole - Press-Fit |
|---------------------------|--------------------------|

|                                    |        |
|------------------------------------|--------|
| Termination Method to Wire & Cable | Solder |
|------------------------------------|--------|

|                  |                               |
|------------------|-------------------------------|
| Insertion Method | Hand/Semi-Automatic/Automatic |
|------------------|-------------------------------|

### Dimensions

|                             |                                |
|-----------------------------|--------------------------------|
| PCB Thickness (Recommended) | .79 – 3.18 mm [.031 – .125 in] |
|-----------------------------|--------------------------------|

|               |                   |
|---------------|-------------------|
| Socket Length | 4.01 mm [.158 in] |
|---------------|-------------------|

|                   |                   |
|-------------------|-------------------|
| PCB Hole Diameter | 1.32 mm [.052 in] |
|-------------------|-------------------|

|           |             |
|-----------|-------------|
| Wire Size | 25 – 22 AWG |
|-----------|-------------|

|                           |                              |
|---------------------------|------------------------------|
| Mating Pin Diameter Range | .51 – .66 mm [.02 – .026 in] |
|---------------------------|------------------------------|

### Usage Conditions

|                             |                             |
|-----------------------------|-----------------------------|
| Operating Temperature Range | -65 – 125 °C [-85 – 257 °F] |
|-----------------------------|-----------------------------|

### Operation/Application

|                        |           |
|------------------------|-----------|
| Solder Process Feature | Anti-Flux |
|------------------------|-----------|

|                     |                |
|---------------------|----------------|
| Circuit Application | Power & Signal |
|---------------------|----------------|

### Packaging Features

|                  |      |
|------------------|------|
| Packaging Method | Reel |
|------------------|------|

|                    |       |
|--------------------|-------|
| Packaging Quantity | 10000 |
|--------------------|-------|

### Other

|                 |                  |
|-----------------|------------------|
| Spring Material | Beryllium Copper |
|-----------------|------------------|

## Product Compliance

For compliance documentation, visit the product page on [TE.com](https://www.te.com)>

|                              |           |
|------------------------------|-----------|
| EU RoHS Directive 2011/65/EU | Compliant |
|------------------------------|-----------|

|                             |           |
|-----------------------------|-----------|
| EU ELV Directive 2000/53/EC | Compliant |
|-----------------------------|-----------|

|   |   |
|---|---|
| China RoHS 2 Directive MIIT Order No 32, 2016 | 有害物质含量符合标准要求 No Restricted Substance(s) Above Threshold |
|---|---|

|  |   |
|--|---|
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JUNE 2025 (250)<br>Candidate List Declared Against: JUNE 2024 (241)<br>Does not contain REACH SVHC |
|--|---|

|                 |                                       |
|-----------------|---------------------------------------|
| Halogen Content | Low Halogen - Br, Cl, F < 900 ppm per |
|-----------------|---------------------------------------|



homogenous material. Also BFR/CFR/PVC Free

Solder Process Capability

Pin-in-Paste capable to 260°C

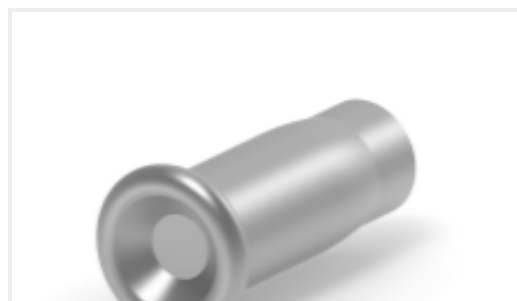
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

### Compatible Parts



TE Part # 1-5645953-5  
SOCKET,MIN-SPR B-N SN-AU SER-2



TE Part # 5645953-2  
SOCKET,MIN-SPR B-N SN-AU SER-2

### Customers Also Bought



TE Part #2-32947-1  
PG R 22-16 COMM 22-18 MIL 6



TE Part #60598-3  
058PIN REC IS 22-20 010TPPHBZ



TE Part #171822-5  
EIS REC. HSG 5P-NATURAL



TE Part #171825-5  
5 POS EIS POST HDR



TE Part #205168-1  
AMPLIMITE,ASY,PLUG,STD,109,4



TE Part #1123721-1  
EP CONN. REC CONTACT



TE Part #3-1437646-3  
3PCV-02-006=3PCV ASSEMBLY



TE Part #1757820-4  
AMPLIMITE,ASY,RCPT,STD,109,ZN,4



## Documents

### Product Drawings

[SOCKET,MIN-SPR B-N SN-AU SER-2](#)

English

### CAD Files

[3D PDF](#)

3D

Customer View Model

[ENG\\_CVM\\_CVM\\_1-5645953-2\\_O.2d\\_dxf.zip](#)

English

Customer View Model

[ENG\\_CVM\\_CVM\\_1-5645953-2\\_O.3d\\_igs.zip](#)

English

Customer View Model

[ENG\\_CVM\\_CVM\\_1-5645953-2\\_O.3d\\_stp.zip](#)

English

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### Product Specifications

[Product Specification](#)

English